SCAN90004 4-Channel LVDS Buffer/Repeater with Pre-Emphasis

Check for Samples: SCAN90004

FEATURES

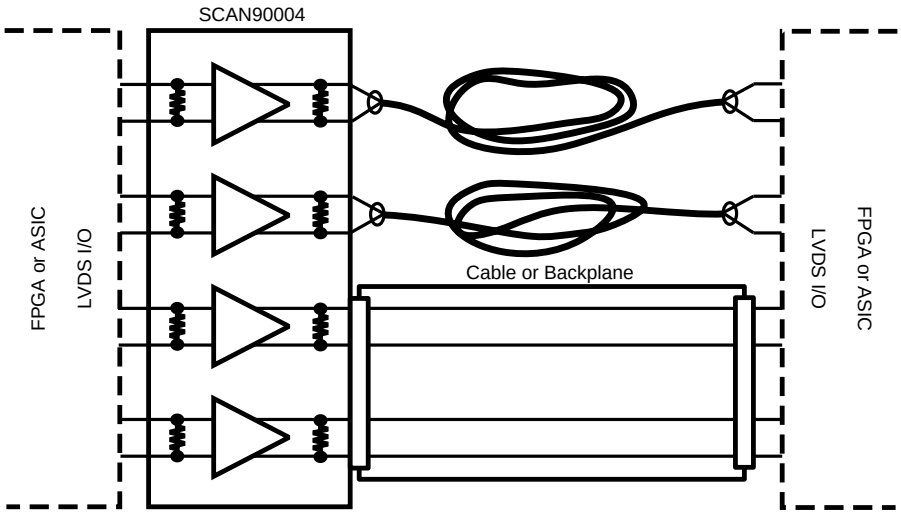
- **1.5 Gbps Maximum Data Rate Per Channel**
- **Configurable Pre-emphasis Drives Lossy Backplanes and Cables**
- **Low Output Skew and Jitter**
- **LVDS/CML/LVPECL Compatible Input, LVDS Output**
- **On-chip 100Ω Input and Output Termination**
- **12 kV ESD Protection on LVDS Outputs**
- **IEEE 1149.1 JTAG Interface**
- **IEEE 1149.6 Limited Capability**
- **Fault Insertion**
- **Single 3.3V Supply**
- **Very Low Power Consumption**
- **Industrial -40 to +85°C Temperature Range**
- **Small TQFP Package Footprint**
- **See DS90LV004 for Non-JTAG Version**

DESCRIPTION

The SCAN90004 is a four channel 1.5 Gbps LVDS buffer/repeater. High speed data paths and flow-through pinout minimize internal device jitter and simplify board layout, while configurable pre-emphasis overcomes ISI jitter effects from lossy backplanes and cables. The differential inputs interface to LVDS, and Bus LVDS signals such as those on TI's 10-, 16-, and 18- bit Bus LVDS SerDes, as well as CML and LVPECL. The differential inputs and outputs are internally terminated with a 100Ω resistor to improve performance and minimize board space. The repeater function is especially useful for boosting signals for longer distance transmission over lossy cables and backplanes.

Integrated testability circuitry supports IEEE1149.1 (JTAG) on single-ended LVTTL/CMOS I/O and limited IEEE1149.6 capability on high-speed differential LVDS interconnects. The 3.3V supply, CMOS process, and LVDS I/O ensure stable high performance at low power over the entire industrial -40 to +85°C temperature range.

Typical Application



Block and Connection Diagrams

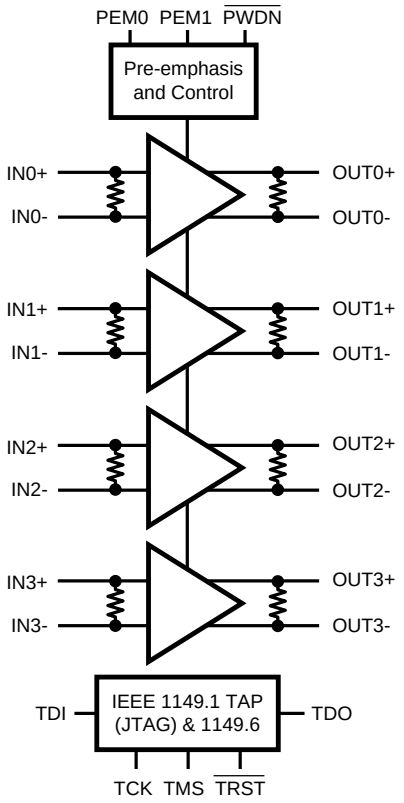


Figure 1. SCAN90004 Block Diagram

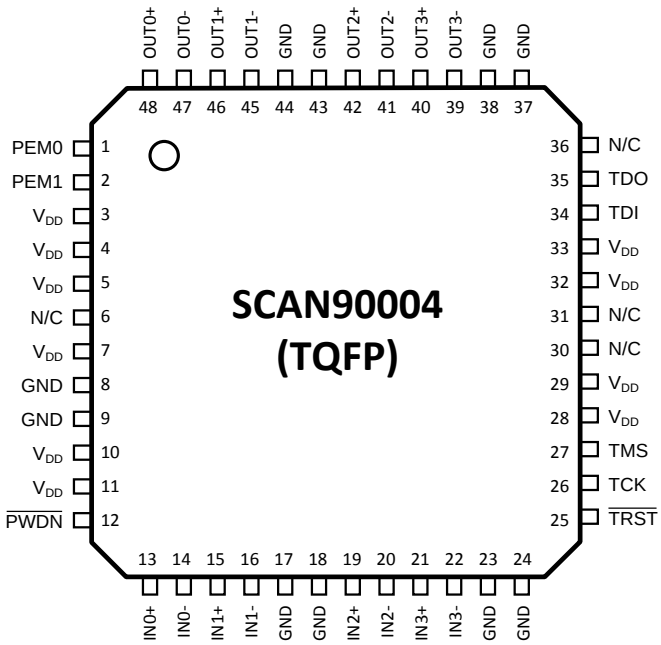


Figure 2. Pinout - Top View

Pin Descriptions

Pin Name	TQFP Pin Number	I/O, Type	Description
DIFFERENTIAL INPUTS			
IN0+ IN0−	13 14	I, LVDS	Channel 0 inverting and non-inverting differential inputs.
IN1+ IN1−	15 16	I, LVDS	Channel 1 inverting and non-inverting differential inputs.
IN2+ IN2−	19 20	I, LVDS	Channel 2 inverting and non-inverting differential inputs.
IN3+ IN3−	21 22	I, LVDS	Channel 3 inverting and non-inverting differential inputs.
DIFFERENTIAL OUTPUTS			
OUT0+ OUT0−	48 47	O, LVDS	Channel 0 inverting and non-inverting differential outputs. (1)
OUT1+ OUT1−	46 45	O, LVDS	Channel 1 inverting and non-inverting differential outputs. (1)
OUT2+ OUT2−	42 41	O, LVDS	Channel 2 inverting and non-inverting differential outputs. (1)
OUT3+ OUT3-	40 39	O, LVDS	Channel 3 inverting and non-inverting differential outputs. (1)
DIGITAL CONTROL INTERFACE			
$\overline{\text{PWDN}}$	12	I, LVTTL	A logic low at $\overline{\text{PWDN}}$ activates the hardware power down mode.

(1) The LVDS outputs do not support a multidrop (BLVDS) environment. The LVDS output characteristics of the SCAN90004 device have been optimized for point-to-point backplane and cable applications.

Pin Descriptions (continued)

Pin Name	TQFP Pin Number	I/O, Type	Description
PEM0 PEM1	1 2	I, LVTTL	Pre-emphasis Control Inputs (affects all Channels)
TDI	34	I, LVTTL	Test Data Input to support IEEE 1149.1 features
TDO	35	O, LVTTL	Test Data Output to support IEEE 1149.1 features
TMS	27	I, LVTTL	Test Mode Select to support IEEE 1149.1 features
TCK	26	I, LVTTL	Test Clock to support IEEE 1149.1 features
$\overline{TRST}$	25	I, LVTTL	Test Reset to support IEEE 1149.1 features
POWER			
V_{DD}	3, 4, 5, 7, 10, 11, 28, 29, 32, 33	I, Power	V_{DD} = 3.3V, ±5%
GND	8, 9, 17, 18, 23, 24, 37, 38, 43, 44	I, Power	Ground
N/C	6, 30, 31, 36		No Connect

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings (1)

Supply Voltage (V_{DD})		−0.3V to +4.0V
CMOS Input Voltage		-0.3V to (V_{DD}+0.3V)
LVDS Input Voltage (2)		-0.3V to (V_{DD}+0.3V)
LVDS Output Voltage		-0.3V to (V_{DD}+0.3V)
LVDS Output Short Circuit Current		+40 mA
Junction Temperature		+150°C
Storage Temperature		−65°C to +150°C
Lead Temperature (Solder, 4sec)		260°C
Max Pkg Power Capacity @ 25°C		1.64W
Thermal Resistance (θ_{JA})		76°C/W
Package Derating above +25°C		13.2mW/°C
ESD Last Passing Voltage (LVDS output pins)	HBM, 1.5kΩ, 100pF	12kV
	EIAJ, 0Ω, 200pF	250V
ESD Last Passing Voltage (All other pins)	HBM, 1.5kΩ, 100pF	8kV
	EIAJ, 0Ω, 200pF	250V

(1) Absolute maximum ratings are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. TI does not recommend operation of products outside of recommended operation conditions.
(2) V_{ID} max < 2.4V

Recommended Operating Conditions

Supply Voltage (V_{DD})	3.15V to 3.45V
Input Voltage (V_I) (1)	0V to V_{DD}
Output Voltage (V_O)	0V to V_{DD}
Operating Temperature (T_A) Industrial	−40°C to +85°C

(1) V_{ID} max < 2.4V

Electrical Characteristics

Over recommended operating supply and temperature ranges unless other specified.

Symbol	Parameter	Conditions	Min	Typ (1)	Max	Units
LVTTL DC SPECIFICATIONS ($\overline{PWDN}$, PEM0, PEM1, TDI, TDO, TCK, TMS, $\overline{TRST}$)						
V_{IH}	High Level Input Voltage		2.0		V_{DD}	V
V_{IL}	Low Level Input Voltage		GND		0.8	V
I_{IH}	High Level Input Current	$V_{IN} = V_{DD} = V_{DDMAX}$	−10		+10	µA
I_{IL}	Low Level Input Current	$V_{IN} = V_{SS}$, $V_{DD} = V_{DDMAX}$	−10		+10	µA
I_{ILR}	Low Level Input Current	TDI, TMS, $\overline{TRST}$	-40		-200	µA
C_{IN1}	Input Capacitance	Any Digital Input Pin to V_{SS}		3.5		pF
C_{OUT1}	Output Capacitance	Any Digital Output Pin to V_{SS}		5.5		pF
V_{CL}	Input Clamp Voltage	I_{CL} = −18 mA	−1.5	−0.8		V
V_{OH}	High Level Output Voltage (TDO)	I_{OH} = −12 mA, V_{DD} = 3.15 V	2.4			V
		I_{OH} = −100 µA, V_{DD} = 3.15 V	V_{DD}-0.2			V
V_{OL}	Low Level Output Voltage (TDO)	I_{OL} = 12 mA, V_{DD} = 3.15 V			0.5	V
		I_{OL} = 100 µA, V_{DD} = 3.15 V			0.2	V
I_{OS}	Output Short Circuit Current	TDO	−15		−125	mA
I_{OZ}	Output TRI-STATE Current	TDO	−10		+10	µA
LVDS INPUT DC SPECIFICATIONS (INn±)						
V_{TH}	Differential Input High Threshold (2)	V_{CM} = 0.8V to 3.4V, V_{DD} = 3.45V		0	100	mV
V_{TL}	Differential Input Low Threshold (2)	V_{CM} = 0.8V to 3.4V, V_{DD} = 3.45V	−100	0		mV
V_{ID}	Differential Input Voltage	V_{CM} = 0.8V to 3.4V, V_{DD} = 3.45V	100		2400	mV
V_{CMR}	Common Mode Voltage Range	V_{ID} = 150 mV, V_{DD} = 3.45V	0.05		3.40	V
C_{IN2}	Input Capacitance	IN+ or IN− to V_{SS}		5.2		pF
I_{IN}	Input Current	V_{IN} = 3.45V, $V_{DD} = V_{DDMAX}$	−10		+10	µA
		V_{IN} = 0V, $V_{DD} = V_{DDMAX}$	−10		+10	µA
LVDS OUTPUT DC SPECIFICATIONS (OUTn±)						
V_{OD}	Differential Output Voltage, 0% Pre-emphasis (2)	R_L = 100Ω external resistor between OUT+ and OUT−	250	500	600	mV
ΔV_{OD}	Change in V_{OD} between Complementary States		-35		35	mV
V_{OS}	Offset Voltage (3)		1.05	1.18	1.475	V
ΔV_{OS}	Change in V_{OS} between Complementary States		-35		35	mV
I_{OS}	Output Short Circuit Current	OUT+ or OUT− Short to GND		−60	−90	mA
C_{OUT2}	Output Capacitance	OUT+ or OUT− to GND when TRI-STATE		5.5		pF
SUPPLY CURRENT (Static)						
I_{CC}	Supply Current	All inputs and outputs enabled and active, terminated with external differential load of 100Ω between OUT+ and OUT-, 0% pre-emphasis		117	140	mA
I_{CCZ}	Supply Current - Power Down Mode	$\overline{PWDN}$ = L, 0% pre-emphasis		2.7	6	mA
SWITCHING CHARACTERISTICS—LVDS OUTPUTS						
t_{LHT}	Differential Low to High Transition Time	Use an alternating 1 and 0 pattern at 200 Mb/s, measure between 20% and 80% of V_{OD}. (4)		210	300	ps
t_{HLT}	Differential High to Low Transition Time			210	300	ps

(1) Typical parameters are measured at V_{DD} = 3.3V, T_A = 25°C. They are for reference purposes, and are not production-tested.
(2) Differential output voltage V_{OD} is defined as ABS(OUT+–OUT−). Differential input voltage V_{ID} is defined as ABS(IN+–IN−).
(3) Output offset voltage V_{OS} is defined as the average of the LVDS single-ended output voltages at logic high and logic low states.
(4) Not production tested. Specified by a statistical analysis on a sample basis at the time of characterization.

Electrical Characteristics (continued)

Over recommended operating supply and temperature ranges unless other specified.

Symbol	Parameter	Conditions	Min	Typ (1)	Max	Units
t_{PLHD}	Differential Low to High Propagation Delay	Use an alternating 1 and 0 pattern at 200 Mb/s, measure at 50% V_{OD} between input to output.		2.0	3.2	ns
t_{PHLD}	Differential High to Low Propagation Delay			2.0	3.2	ns
t_{SKD1}	Pulse Skew	$\lvert t_{PLHD} - t_{PHLD} \rvert$ (4)		25	80	ps
t_{SKCC}	Output Channel to Channel Skew	Difference in propagation delay (t_{PLHD} or t_{PHLD}) among all output channels. (4)		50	125	ps
t_{SKP}	Part to Part Skew (4)	Common edge, parts at same temp and V_{CC} (4)			1.1	ns
t_{JIT}	Jitter (0% Pre-emphasis) (5)	RJ - Alternating 1 and 0 at 750 MHz (6)		1.1	1.5	psrms
		DJ - K28.5 Pattern, 1.5 Gbps (7)		43	62	psp-p
		TJ - PRBS 2^{23}-1 Pattern, 1.5 Gbps (8)		35	85	psp-p
t_{ON}	LVDS Output Enable Time	Time from $\overline{PWDN}$ to OUT± change from TRI-STATE to active.			300	ns
t_{OFF}	LVDS Output Disable Time	Time from $\overline{PWDN}$ to OUT± change from active to TRI-STATE.			12	ns
SWITCHING CHARACTERISTICS—SCAN FEATURES						
f_{MAX}	Maximum TCK Clock Frequency	R_L = 500Ω, C_L = 35 pF	25.0			MHz
t_S	TDI to TCK, H or L		3.0			ns
t_H	TDI to TCK, H or L		0.5			ns
t_S	TMS to TCK, H or L		2.5			ns
t_H	TMS to TCK, H or L		0.5			ns
t_W	TCK Pulse Width, H or L		10.0			ns
t_W	$\overline{TRST}$ Pulse Width, L		2.5			ns
t_{REC}	Recovery Time, $\overline{TRST}$ to TCK		1.0			ns

(5) Jitter is not production tested, but specified through characterization on a sample basis.
(6) Random Jitter, or RJ, is measured RMS with a histogram including 1500 histogram window hits. The input voltage = V_{ID} = 500mV, 50% duty cycle at 750MHz, t_r = t_f = 50ps (20% to 80%).
(7) Deterministic Jitter, or DJ, is measured to a histogram mean with a sample size of 350 hits. The input voltage = V_{ID} = 500mV, K28.5 pattern at 1.5 Gbps, t_r = t_f = 50ps (20% to 80%). The K28.5 pattern is repeating bit streams of (0011111010 1100000101).
(8) Total Jitter, or TJ, is measured peak to peak with a histogram including 3500 window hits. Stimulus and fixture jitter has been subtracted. The input voltage = V_{ID} = 500mV, 2^{23}-1 PRBS pattern at 1.5 Gbps, t_r = t_f = 50ps (20% to 80%).

FEATURE DESCRIPTIONS

INTERNAL TERMINATIONS

The SCAN90004 has integrated termination resistors on both the input and outputs. The inputs have a 100Ω resistor across the differential pair, placing the receiver termination as close as possible to the input stage of the device. The LVDS outputs also contain an integrated 100Ω ohm termination resistor, this resistor is used to reduce the effects of Near End Crosstalk (NEXT) and does not take the place of the 100 ohm termination at the inputs to the receiving device. The integrated terminations improve signal integrity and decrease the external component count resulting in space savings.

OUTPUT CHARACTERISTICS

The output characteristics of the SCAN90004 have been optimized for point-to-point backplane and cable applications, and are not intended for multipoint or multidrop signaling.

POWERDOWN MODE

The $\overline{\text{PWDN}}$ input activates a hardware powerdown mode. When the powerdown mode is active ($\overline{\text{PWDN}}$=L), all input and output buffers and internal bias circuitry are powered off and disabled. Outputs are tri-stated in powerdown mode. JTAG Circuitry is active per the IEEE standard, but does not switch unless TCK is toggling. When exiting powerdown mode, there is a delay associated with turning on bandgap references and input/output buffer circuits as indicated in the LVDS Output Switching Characteristics

Upon asserting the power down function ($\overline{\text{PWDN}}$ = Low), and if the Pre-emphasis feature is enable, it is possible for the driver output to source current for a short amount of time lifting the output common mode to V_{DD}. To prevent this occurrence, a load discharge pull down path can be used on either output (1 kΩ to ground recommended). Alternately, a commonly deployed external failsafe network will also provide this path (see INPUT FAILSAFE BIASING). The occurrence of this is application dependant, and parameters that will affect if this is of concern include: AC coupling, use of the powerdown feature, presence of the discharge path, presence of the failsafe biasing, the usage of the pre-emphasis feature, and input characteristics of the downstream LVDS Receiver.

PRE-EMPHASIS

Pre-emphasis dramatically reduces ISI jitter from long or lossy transmission media. Two pins are used to select the pre-emphasis level for all outputs: off, low, medium, or high.

Table 1. Pre-emphasis Control Selection Table

PEM1	PEM0	Pre-Emphasis
0	0	Off
0	1	Low
1	0	Medium
1	1	High

INPUT FAILSAFE BIASING

Failsafe biasing of the LVDS link should be considered if the downstream Receiver is ON and enabled when the source is in TRI-STATE, powered off, or removed. This will set a valid known input state to the active receiver. This is accomplished by using a pull up resistor to V_{DD} on the 'plus' line, and a pull down resistor to GND on the 'minus' line. Resistor values are in the 750 Ω to several k Ω range. The exact value depends upon the desired common mode bias point, termination resistor(s) and desired input differential voltage setting. Please refer to application note AN-1194 (SNLA051) "Failsafe Biasing of LVDS interfaces" for more information and a general discussion.

Design-for-Test (DfT) Features

IEEE 1149.1 (JTAG) SUPPORT

The SCAN90004 supports a fully compliant IEEE 1149.1 interface. The Test Access Port (TAP) provides access to boundary scan cells at each LVTTL I/O on the device for interconnect testing. Differential pins are included in the same boundary scan chain but instead contain IEEE1149.6 cells. IEEE1149.6 is the improved IEEE standard for testing high-speed differential signals.

Refer to the BSDL file located on TI's website for the details of the SCAN90004 IEEE 1149.1 implementation.

IEEE 1149.6 SUPPORT

AC-coupled differential interconnections on very high speed (1+ Gbps) data paths are not testable using traditional IEEE 1149.1 techniques. The IEEE 1149.1 structures and methods are intended to test static (DC-coupled), single ended networks. IEEE 1149.6 is targeted for the testing of high-speed differential (including AC coupled) networks. The SCAN90004 includes circuitry to support AC-coupled testing on all differential inputs and outputs and offers limited test capability. The limitations are due to several application specific factors (board layout, capacitor value, data rate etc.), and also IO compliance (LVDS links in general are DC coupled). The SCAN90004 has not been tested for full compliance or full compatibility to the IEEE1149.6 standard. Testing of the device in the targeted application with the appropriate JTAG software will determine what extent of IEEE 1149.6 support is provided by the device.

FAULT INSERTION

Fault Insertion is a technique used to assist in the verification and debug of diagnostic software. During system testing faults are "injected" to simulate hardware failure and thus help verify the monitoring software can detect and diagnose these faults. In the SCAN90004 an IEEE1149.1 "stuck-at" instruction can create a stuck-at condition, either high or low, on any pin or combination of pins. A more detailed description of the stuck-at feature can be found in TI Applications note AN-1313 (SNLA060).

Application Information

INPUT INTERFACING

The SCAN90004 accepts differential signals and allow simple AC or DC coupling. With a wide common mode range, the SCAN90004 can be DC-coupled with all common differential drivers (i.e. LVPECL, LVDS, CML). The following three figures illustrate typical DC-coupled interface to common differential drivers. Note that the SCAN90004 inputs are internally terminated with a 100Ω resistor.

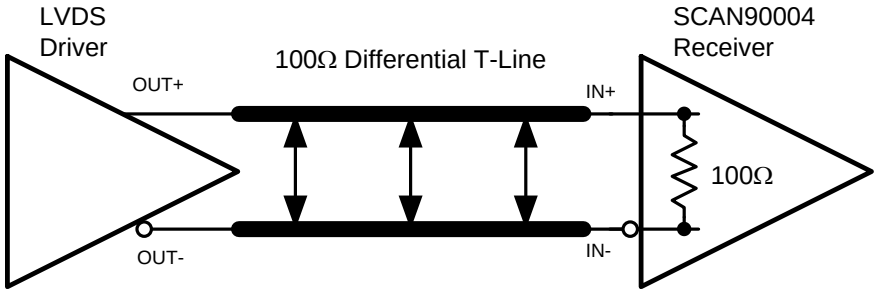


Figure 3. Typical LVDS Driver DC-Coupled Interface to SCAN90004 Input

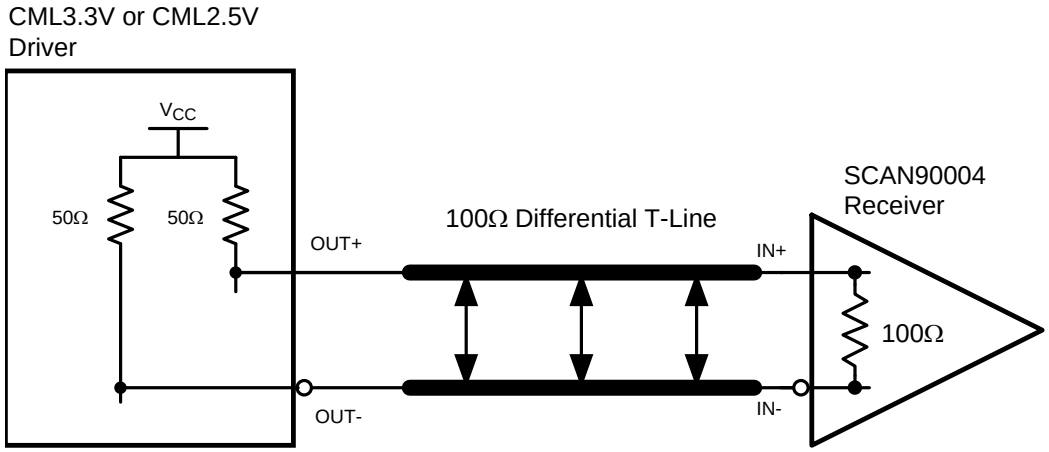


Figure 4. Typical CML Driver DC-Coupled Interface to SCAN90004 Input

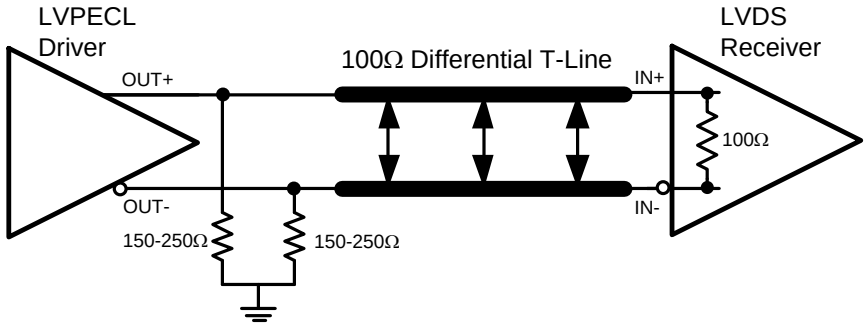


Figure 5. Typical LVPECL Driver DC-Coupled Interface to SCAN90004 Input

OUTPUT INTERFACING

The SCAN90004 outputs signals that are compliant to the LVDS standard. Their outputs can be DC-coupled to most common differential receivers. Figure 6 illustrates typical DC-coupled interface to common differential receivers and assumes that the receivers have high impedance inputs. While most differential receivers have a common mode input range that can accommodate LVDS compliant signals, it is recommended to check respective receiver's data sheet prior to implementing the suggested interface implementation.

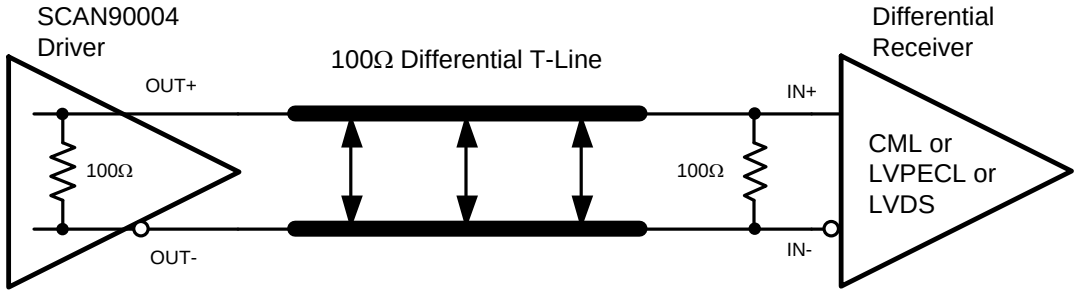
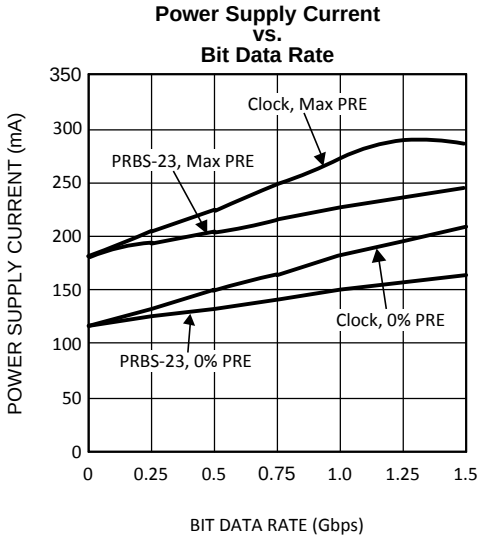


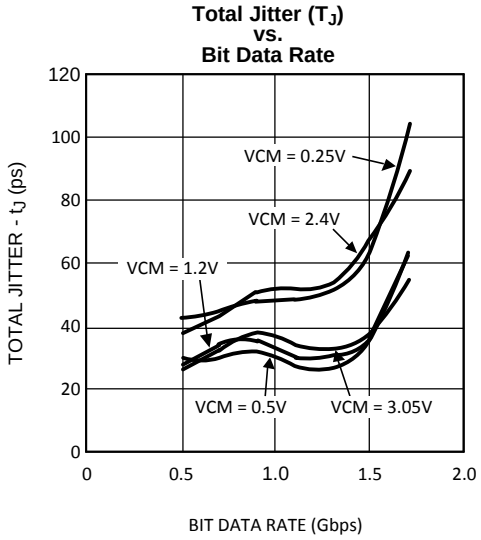
Figure 6. Typical SCAN90004 Output DC-Coupled Interface to an LVDS, CML or LVPECL Receiver

Typical Performance Characteristics



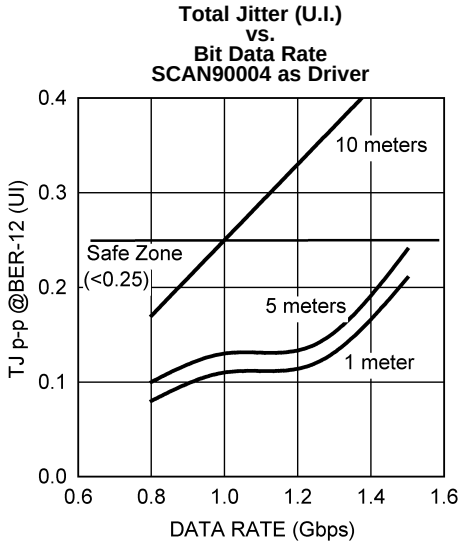
Dynamic power supply current was measured while running a clock or PRBS 2^{23}-1 pattern with all 4 channels active.
V_{CC} = 3.3V, T_A = +25°C, V_{ID} = 0.5V, V_{CM} = 1.2V

Figure 7.



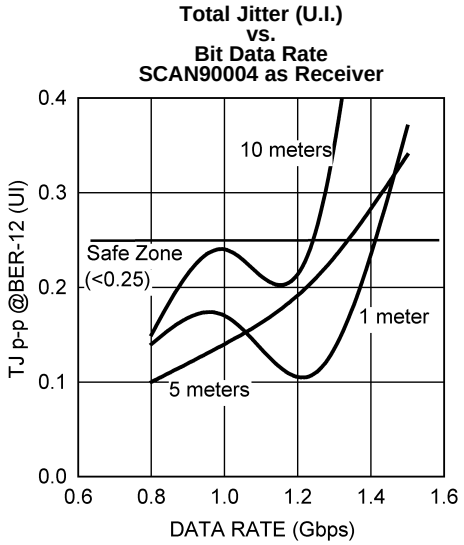
Total Jitter measured at 0V differential while running a PRBS 2^{23}-1 pattern with a single channel active.
V_{CC} = 3.3V, T_A = +25°C, V_{ID} = 0.5V, 0% Pre-emphasis

Figure 8.



Total Jitter measured while SCAN90004 output is driving a PRBS 2^7-1 NRZ pattern with a single active channel across a Belden 1700A cable.
V_{CC} = 3.3V, T_A = +25°C, V_{ID} = 0.5V, 0% Pre-emphasis.
Data measured at end of specified cable length.

Figure 9.

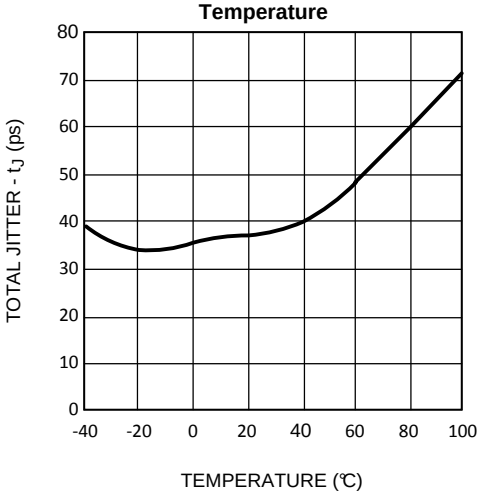


Total Jitter measured at SCAN90004 receiver outputs after receiving a PRBS 2^7-1 NRZ pattern over the specified cable length.
V_{CC} = 3.3V, T_A = +25°C, V_{ID} = 0.5V,
data collected at receiver outputs,
receiver located at end of specified Belden 1700A cable length.

Figure 10.

Typical Performance Characteristics (continued)

Total Jitter (T_J) vs. Temperature



Total Jitter measured at 0V differential
while running a PRBS 2^{23}-1 pattern
with a single channel active.
V_{CC} = 3.3V, V_{ID} = 0.5V, V_{CM} = 1.2V, 1.5
Gbps data rate, 0% Pre-emphasis

Figure 11.

Positive Edge Transition vs. Pre-emphasis Level

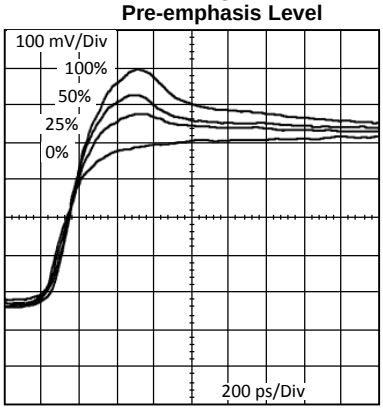


Figure 12.

REVISION HISTORY

Changes from Revision O (April 2013) to Revision P	Page
• Changed layout of National Data Sheet to TI format	10

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SCAN90004TVS	ACTIVE	TQFP	PFB	48	250	TBD	Call TI	Call TI	-40 to 85	SCAN 90004TVS	Samples
SCAN90004TVS/NOPB	ACTIVE	TQFP	PFB	48	250	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 85	SCAN 90004TVS	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

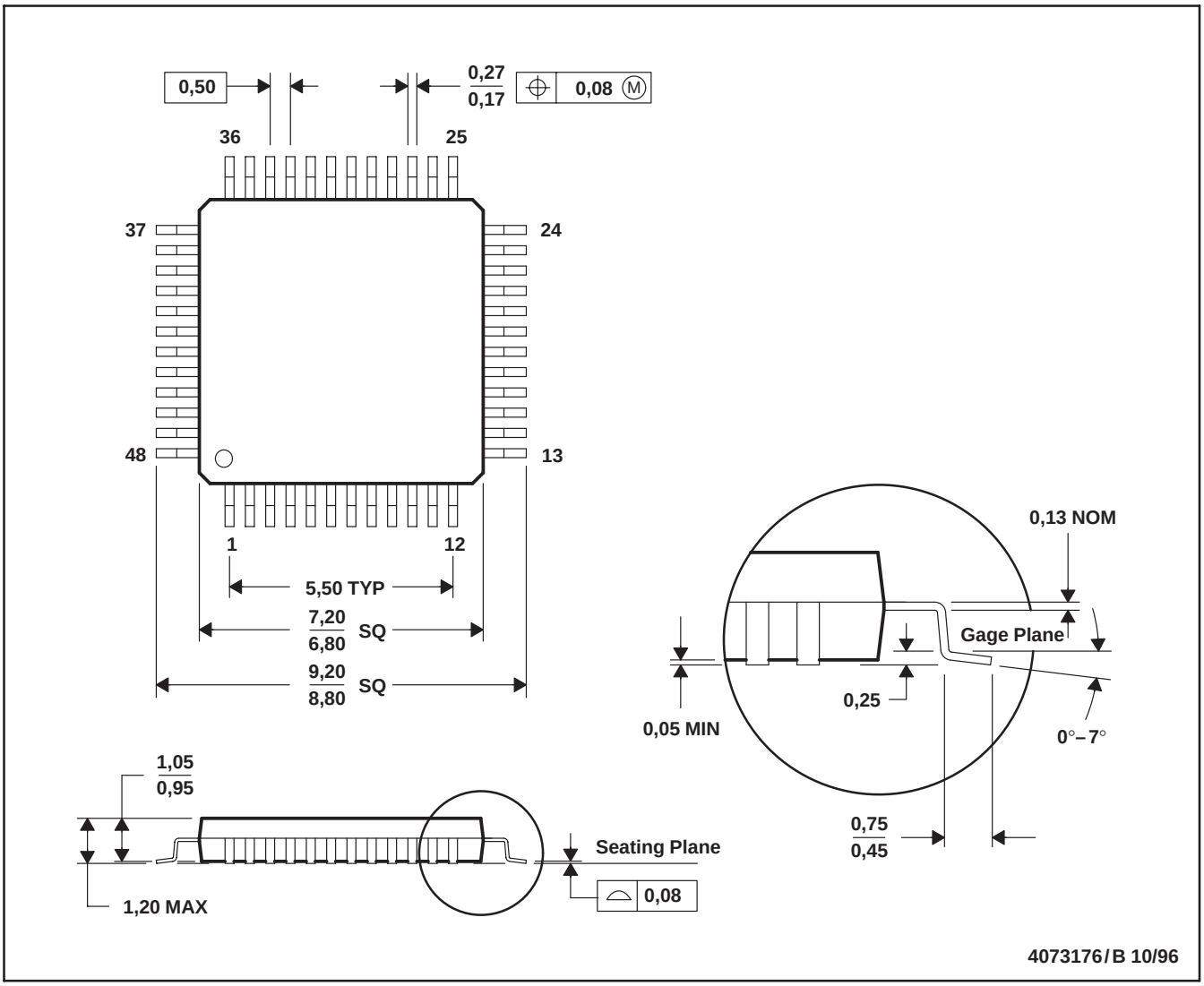
(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

MTQF019A – JANUARY 1995 – REVISED JANUARY 1998

PFB (S-PQFP-G48) **PLASTIC QUAD FLATPACK**



NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-026

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265